



## FQB10N20L / FQI10N20L

### 200V LOGIC N-Channel MOSFET

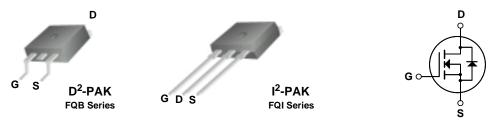
### **General Description**

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology is especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation modes. These devices are well suited for high efficiency switching DC/DC converters, switch mode power supplies, and motor control.

#### **Features**

- 10A, 200V,  $R_{DS(on)} = 0.36\Omega @V_{GS} = 10 \text{ V}$
- Low gate charge (typical 13 nC)
- Low Crss (typical 14 pF)
- Fast switching
- · 100% avalanche tested
- · Improved dv/dt capability
- Low level gate drive requirement allowing direct operation from logic drivers



### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter		FQB10N20L / FQI10N20L	Units	
V <sub>DSS</sub>	Drain-Source Voltage		200	V	
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25	°C)	10	Α	
	- Continuous (T <sub>C</sub> = 10	0°C)	6.3	Α	
$I_{DM}$	Drain Current - Pulsed	(Note 1)	40	Α	
$V_{GSS}$	Gate-Source Voltage		± 20	V	
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	180	mJ	
I <sub>AR</sub>	Avalanche Current	(Note 1)	10	Α	
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	8.7	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	5.5	V/ns	
P <sub>D</sub>	Power Dissipation (T <sub>A</sub> = 25°C) *		3.13	W	
	Power Dissipation (T <sub>C</sub> = 25°C)		87	W	
	- Derate above 25°C		0.7	W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C	
T <sub>L</sub>	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	

### **Thermal Characteristics**

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		1.44	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

<sup>\*</sup> When mounted on the minimum pad size recommended (PCB Mount)

	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	200			V
$\Delta BV_{DSS}$ / $\Delta T_{J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu A$ , Referenced to 25°C		0.18		V/°C
I <sub>DSS</sub>	Zero Osto Valta va Basis Osmani	V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V			1	μΑ
	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 160 V, T <sub>C</sub> = 125°C			10	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 20 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -20 V, V <sub>DS</sub> = 0 V			-100	nA
On Cha	aracteristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1.0		2.0	V
R <sub>DS(on)</sub>	Static Drain-Source	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 5.0 A		0.29	0.36	0
- (- /	On-Resistance	$V_{GS} = 5 \text{ V}, I_D = 5.0 \text{ A}$ (Note 4)		0.3	0.38	Ω
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 30 \text{ V}, I_{D} = 5.0 \text{ A}$		10.7		S
C <sub>iss</sub>	ic Characteristics Input Capacitance	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V,		640	830	pF
0						
	Output Capacitance	f = 1.0 MHz		95	125	pF
	Output Capacitance Reverse Transfer Capacitance	f = 1.0 MHz		95 14	125 18	pF pF
C <sub>rss</sub>	Reverse Transfer Capacitance	f = 1.0 MHz		14	18	pF
Switch	Reverse Transfer Capacitance  ing Characteristics  Turn-On Delay Time	f = 1.0 MHz V <sub>DD</sub> = 100 V, I <sub>D</sub> = 10 A,		14	18 35	pF
Switch t <sub>d(on)</sub>	Reverse Transfer Capacitance  ing Characteristics  Turn-On Delay Time  Turn-On Rise Time	$V_{DD} = 100 \text{ V}, I_{D} = 10 \text{ A},$ $R_{G} = 25 \Omega$		14 13 150	35 310	pF ns ns
$C_{rss}$ Switching to the second s	Reverse Transfer Capacitance  ing Characteristics  Turn-On Delay Time  Turn-On Rise Time  Turn-Off Delay Time	V <sub>DD</sub> = 100 V, I <sub>D</sub> = 10 A,		14 13 150 50	35 310 110	ns ns ns
	Reverse Transfer Capacitance  ing Characteristics  Turn-On Delay Time  Turn-On Rise Time  Turn-Off Delay Time  Turn-Off Fall Time	$V_{DD} = 100 \text{ V}, I_{D} = 10 \text{ A},$ $R_{G} = 25 \Omega$ (Note 4, 5)	  	14 13 150 50 95	35 310 110 200	ns ns ns
$\begin{array}{c} \textbf{Switch} \\ \textbf{Switch} \\ \textbf{t}_{d(on)} \\ \textbf{t}_{r} \\ \textbf{t}_{d(off)} \\ \textbf{t}_{f} \\ \textbf{Q}_{g} \end{array}$	Reverse Transfer Capacitance  ing Characteristics  Turn-On Delay Time  Turn-On Rise Time  Turn-Off Delay Time  Turn-Off Fall Time  Total Gate Charge	$V_{DD} = 100 \text{ V}, I_D = 10 \text{ A},$ $R_G = 25 \Omega$ (Note 4, 5) $V_{DS} = 160 \text{ V}, I_D = 10 \text{ A},$	   	13 150 50 95 13	35 310 110 200 17	ns ns ns ns nc
$\begin{array}{c} \textbf{Switch} \\ \textbf{Switch} \\ \textbf{t}_{d(on)} \\ \textbf{t}_{r} \\ \textbf{t}_{d(off)} \\ \textbf{t}_{f} \\ \textbf{Q}_{g} \\ \textbf{Q}_{gs} \end{array}$	Reverse Transfer Capacitance  ing Characteristics  Turn-On Delay Time  Turn-On Rise Time  Turn-Off Delay Time  Turn-Off Fall Time  Total Gate Charge  Gate-Source Charge	$V_{DD} = 100 \text{ V}, I_{D} = 10 \text{ A},$ $R_{G} = 25 \Omega$ (Note 4, 5)		14 13 150 50 95 13 2.4	35 310 110 200 17	ns ns ns nc nC
Switch t <sub>d(on)</sub> t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub>	Reverse Transfer Capacitance  ing Characteristics  Turn-On Delay Time  Turn-On Rise Time  Turn-Off Delay Time  Turn-Off Fall Time  Total Gate Charge	$V_{DD} = 100 \text{ V}, I_D = 10 \text{ A},$ $R_G = 25 \Omega$ (Note 4, 5) $V_{DS} = 160 \text{ V}, I_D = 10 \text{ A},$	   	13 150 50 95 13	35 310 110 200 17	ns ns ns ns
$\begin{array}{c} \textbf{Switch} \\ \textbf{Switch} \\ \textbf{t}_{d(on)} \\ \textbf{t}_{r} \\ \textbf{t}_{d(off)} \\ \textbf{t}_{f} \\ \textbf{Q}_{g} \\ \textbf{Q}_{gs} \\ \textbf{Q}_{gd} \\ \end{array}$	Reverse Transfer Capacitance  ing Characteristics  Turn-On Delay Time  Turn-On Rise Time  Turn-Off Delay Time  Turn-Off Fall Time  Total Gate Charge  Gate-Source Charge	$V_{DD} = 100 \text{ V}, I_D = 10 \text{ A},$ $R_G = 25 \Omega$ (Note 4, 5) $V_{DS} = 160 \text{ V}, I_D = 10 \text{ A},$ $V_{GS} = 5 \text{ V}$ (Note 4, 5)		14 13 150 50 95 13 2.4	35 310 110 200 17	ns ns ns nc nC
$\begin{array}{c} \textbf{Switch} \\ \textbf{Switch} \\ \textbf{t}_{d(on)} \\ \textbf{t}_{r} \\ \textbf{t}_{d(off)} \\ \textbf{t}_{f} \\ \textbf{Q}_{g} \\ \textbf{Q}_{gs} \\ \textbf{Q}_{gd} \\ \end{array}$	Reverse Transfer Capacitance  ing Characteristics  Turn-On Delay Time  Turn-On Rise Time  Turn-Off Delay Time  Turn-Off Fall Time  Total Gate Charge  Gate-Source Charge  Gate-Drain Charge	$V_{DD} = 100 \text{ V}, I_{D} = 10 \text{ A},$ $R_{G} = 25 \Omega \qquad \qquad \text{(Note 4, 5)}$ $V_{DS} = 160 \text{ V}, I_{D} = 10 \text{ A},$ $V_{GS} = 5 \text{ V} \qquad \qquad \text{(Note 4, 5)}$ and Maximum Ratings		14 13 150 50 95 13 2.4	35 310 110 200 17	ns ns ns nc nC
	Reverse Transfer Capacitance  ing Characteristics  Turn-On Delay Time  Turn-On Rise Time  Turn-Off Delay Time  Turn-Off Fall Time  Total Gate Charge  Gate-Source Charge  Gate-Drain Charge  Source Diode Characteristics ar	$V_{DD}$ = 100 V, $I_D$ = 10 A, $R_G$ = 25 $\Omega$ (Note 4, 5) $V_{DS}$ = 160 V, $I_D$ = 10 A, $V_{GS}$ = 5 V (Note 4, 5)		14 13 150 50 95 13 2.4 6.1	35 310 110 200 17 	ns ns ns ns nC nC
$\begin{array}{c} \textbf{C}_{rss} \\ \textbf{Switch} \\ \textbf{t}_{d(on)} \\ \textbf{t}_{r} \\ \textbf{t}_{d(off)} \\ \textbf{t}_{f} \\ \textbf{Q}_{g} \\ \textbf{Q}_{gs} \\ \textbf{Q}_{gd} \\ \\ \textbf{Drain-S} \\ \textbf{I}_{SM} \\ \end{array}$	Reverse Transfer Capacitance  ing Characteristics  Turn-On Delay Time  Turn-On Rise Time  Turn-Off Delay Time  Turn-Off Fall Time  Total Gate Charge  Gate-Source Charge  Gate-Drain Charge  Source Diode Characteristics and Maximum Continuous Drain-Source Diode	$V_{DD}$ = 100 V, $I_D$ = 10 A, $R_G$ = 25 $\Omega$ (Note 4, 5) $V_{DS}$ = 160 V, $I_D$ = 10 A, $V_{GS}$ = 5 V (Note 4, 5)		14 13 150 50 95 13 2.4 6.1	35 310 110 200 17 	ns ns ns nc nC
$\begin{array}{c} \textbf{Switchi} \\ \textbf{Switchi} \\ t_{d(on)} \\ t_r \\ t_{d(off)} \\ t_f \\ Q_g \\ Q_{gs} \\ Q_{gd} \\ \\ \textbf{Drain-S} \\ \textbf{I}_S \\ \end{array}$	Reverse Transfer Capacitance  ing Characteristics  Turn-On Delay Time  Turn-On Rise Time  Turn-Off Delay Time  Turn-Off Fall Time  Total Gate Charge  Gate-Source Charge  Gate-Drain Charge  Source Diode Characteristics ar  Maximum Continuous Drain-Source Diode F	$V_{DD} = 100 \text{ V}, I_D = 10 \text{ A},$ $R_G = 25 \Omega$ (Note 4, 5) $V_{DS} = 160 \text{ V}, I_D = 10 \text{ A},$ $V_{GS} = 5 \text{ V}$ (Note 4, 5)  and Maximum Ratings ode Forward Current		13 150 50 95 13 2.4 6.1	35 310 110 200 17  	ns ns ns nc nC

- $\label{eq:Notes:Notes:1} \begin{tabular}{ll} \textbf{Notes:} \\ \textbf{1. Repetitive Rating: Pulse width limited by maximum junction temperature} \\ \textbf{2. L} = 2.7\text{mH, } |_{AS} = 10\text{A, } V_{DD} = 50\text{V}, R_{G} = 25\ \Omega, Starting } T_{J} = 25^{\circ}\text{C} \\ \textbf{3. } |_{SD} \le 10\text{A, } \text{di/dt} \le 300\text{A/}\mu\text{s, } V_{DD} \le B\text{V}_{DSS}, Starting } T_{J} = 25^{\circ}\text{C} \\ \textbf{4. } \text{Pulse Test: Pulse width} \le 300\mu\text{s, Duty cycle} \le 2\% \\ \textbf{5. Essentially independent of operating temperature} \\ \end{tabular}$

## **Typical Characteristics**

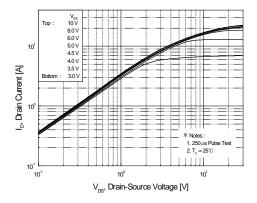


Figure 1. On-Region Characteristics

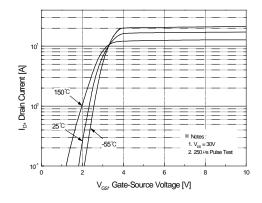


Figure 2. Transfer Characteristics

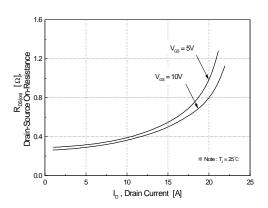


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

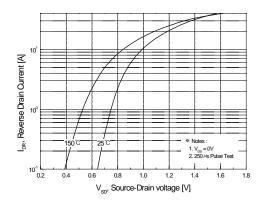


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

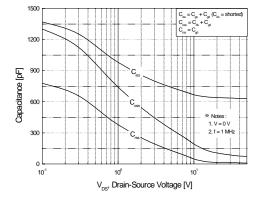


Figure 5. Capacitance Characteristics

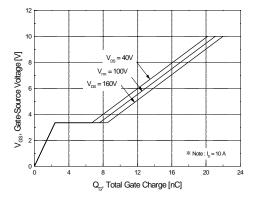


Figure 6. Gate Charge Characteristics

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### Typical Characteristics (Continued)

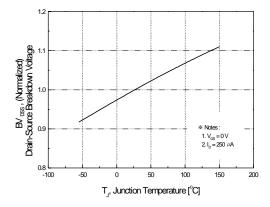
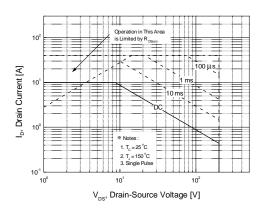


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



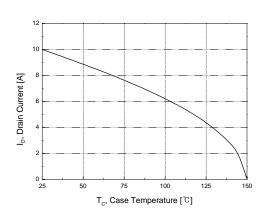


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

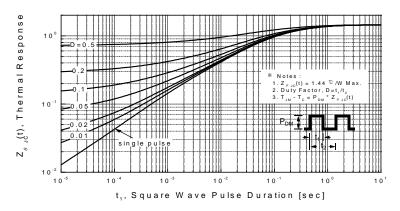
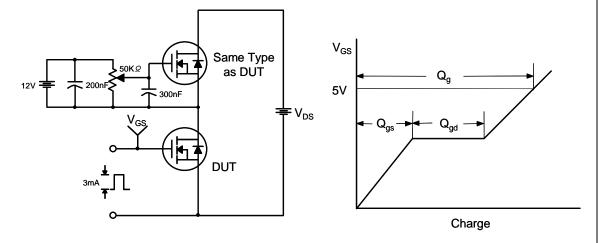


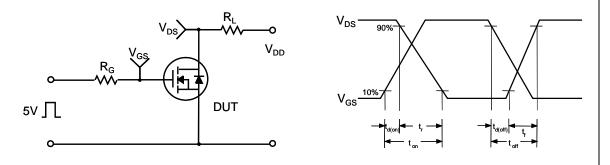
Figure 11. Transient Thermal Response Curve

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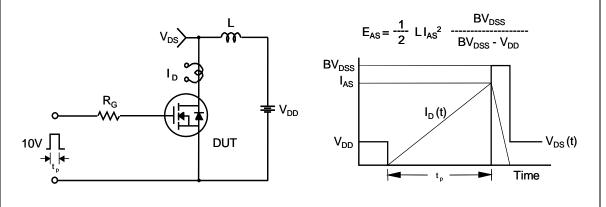
### **Gate Charge Test Circuit & Waveform**



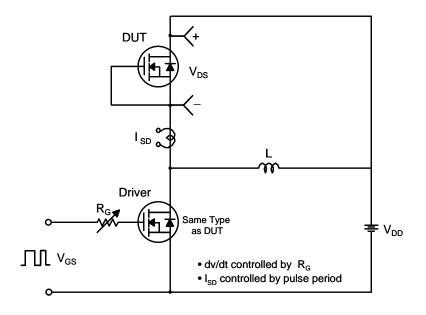
### **Resistive Switching Test Circuit & Waveforms**

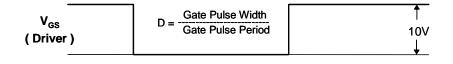


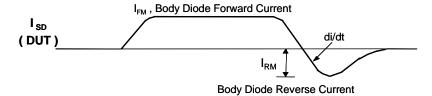
### **Unclamped Inductive Switching Test Circuit & Waveforms**

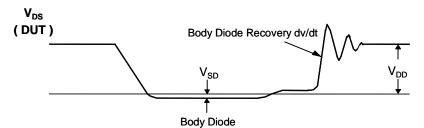


### Peak Diode Recovery dv/dt Test Circuit & Waveforms



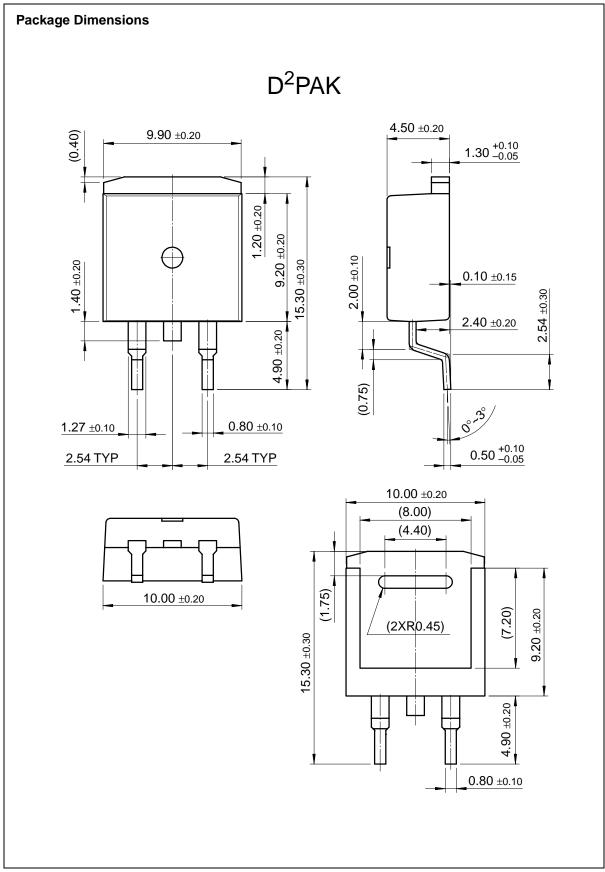


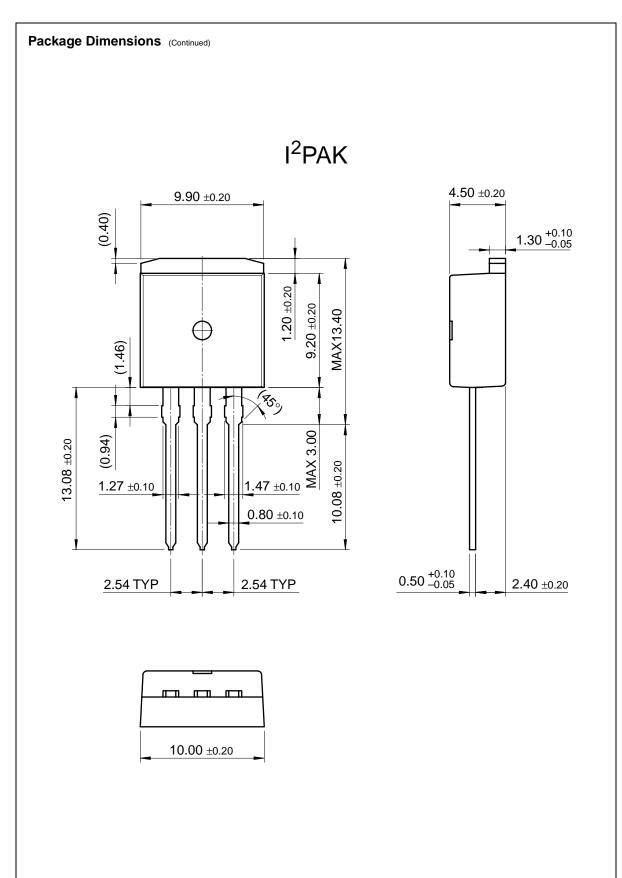




Forward Voltage Drop

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TinyLogic™

UHC™

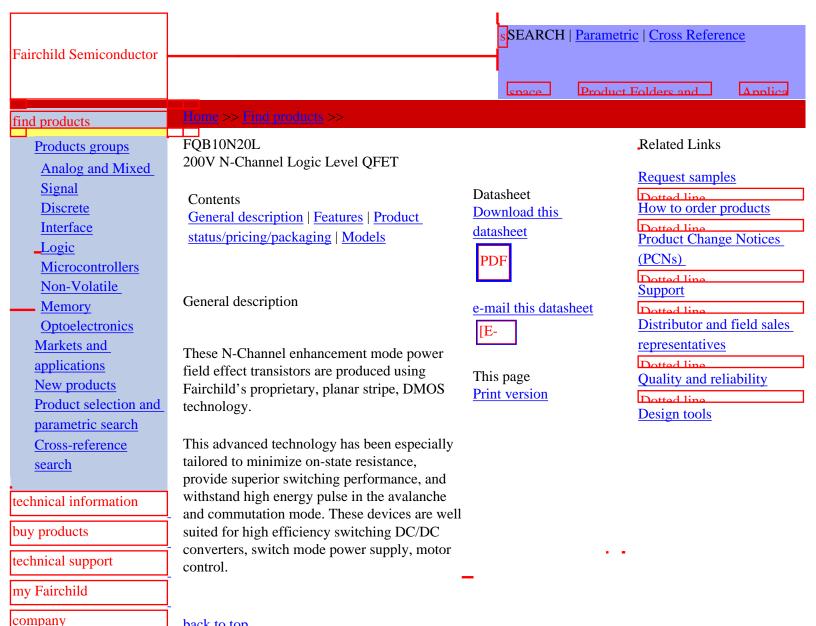
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#### PRODUCT STATUS DEFINITIONS

#### **Definition of Terms**

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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### back to top

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#### back to top

Product status/pricing/packaging

Product	<b>Product status</b>	Pricing*	Package type	Leads	Packing method
FQB10N20LTM	Full Production	\$0.62	TO-263(D2PAK)	2	TAPE REEL

<sup>\* 1,000</sup> piece Budgetary Pricing

### back to top

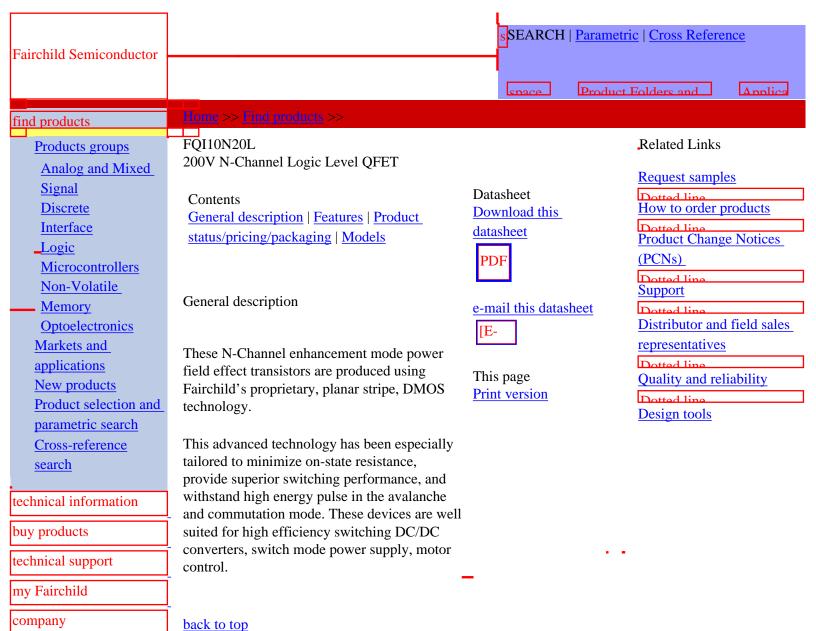
### Models

Package & leads	Condition	Temperature range	Software version	<b>Revision date</b>
PSPICE				
TO-263(D2PAK)-2	Electrical/Thermal	-55°C to 150°C	9.2	Jul 21, 2000

### back to top

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# Features

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### back to top

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Product	<b>Product status</b>	Pricing*	Package type	Leads	Packing method
FQI10N20LTU	Full Production	\$0.62	TO-262(I2PAK)	3	RAIL

<sup>\* 1,000</sup> piece Budgetary Pricing

### back to top

### Models

Package & leads Condition		Temperature range   Software version		Revision date	
PSPICE					
TO-262(I2PAK)-3	Electrical/Thermal	-55°C to 150°C	9	Jul 21, 2000	

### back to top

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